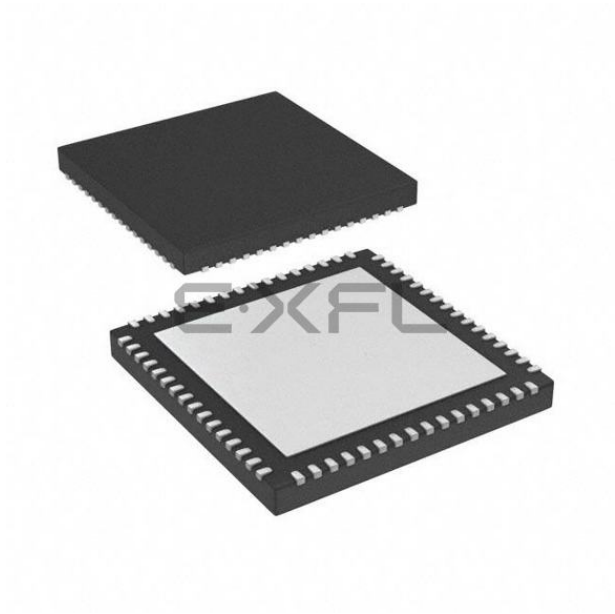

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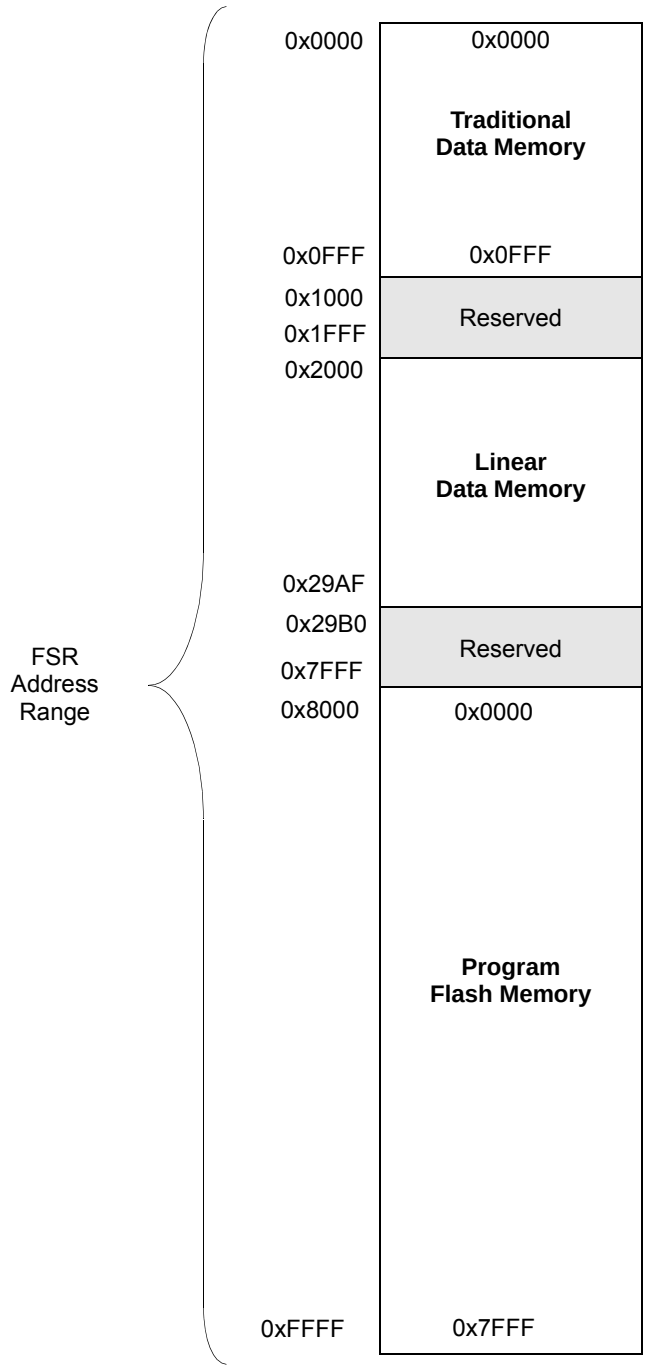
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

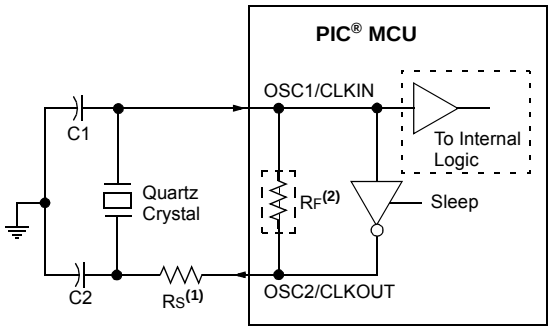
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 17x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1947-i-mr

FIGURE 3-9: INDIRECT ADDRESSING



Note: Not all memory regions are completely implemented. Consult device memory tables for memory limits.

FIGURE 5-3: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)



Note 1: A series resistor (RS) may be required for quartz crystals with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

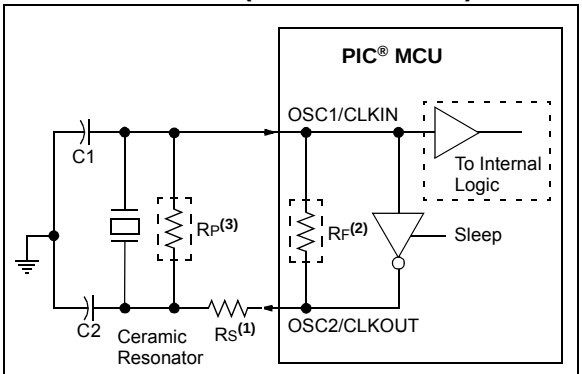
Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Applications Notes:

- *AN826*, *Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices* (DS00826)
- *AN849*, *Basic PICmicro® Oscillator Design* (DS00849)
- *AN943*, *Practical PICmicro® Oscillator Analysis and Design* (DS00943)
- *AN949*, *Making Your Oscillator Work* (DS00949)

FIGURE 5-4: CERAMIC RESONATOR OPERATION (XT OR HS MODE)



Note 1: A series resistor (RS) may be required for ceramic resonators with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

3: An additional parallel feedback resistor (RP) may be required for proper ceramic resonator operation.

5.2.1.3 Oscillator Start-up Timer (OST)

If the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module.

In order to minimize latency between external oscillator start-up and code execution, the Two-Speed Clock Start-up mode can be selected (see **Section 5.4 "Two-Speed Clock Start-up Mode"**).

5.2.1.4 4x PLL

The oscillator module contains a 4x PLL that can be used with both external and internal clock sources to provide a system clock source. The input frequency for the 4x PLL must fall within specifications. See the PLL Clock Timing Specifications in **Section 30.0 "Electrical Specifications"**.

The 4x PLL may be enabled for use by one of two methods:

1. Program the PLLEN bit in Configuration Words to a '1'.
2. Write the SPLLEN bit in the OSCCON register to a '1'. If the PLLEN bit in Configuration Words is programmed to a '1', then the value of SPLLEN is ignored.

9.0 POWER-DOWN MODE (SLEEP)

The Power-Down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 oscillator is unaffected and peripherals that operate from it may continue operation in Sleep.
7. ADC is unaffected, if the dedicated FRC clock is selected.
8. Capacitive Sensing oscillator is unaffected.
9. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
10. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using Timer1 oscillator

I/O pins that are high-impedance inputs should be pulled to V_{DD} or V_{SS} externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include modules such as the DAC and FVR modules. See **Section 17.0 "Digital-to-Analog Converter (DAC) Module"** and **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information on these modules.

9.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 6.11 "Determining the Cause of a Reset"**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction; the device will then call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

12.7 PORTC Registers

PORTC is an 8-bit wide, bidirectional port. The corresponding data direction register is TRISC (Register 12-11). Setting a TRISC bit (= 1) will make the corresponding PORTC pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISC bit (= 0) will make the corresponding PORTC pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 12-1 shows how to initialize an I/O port.

Reading the PORTC register (Register 12-10) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATC).

The TRISC register (Register 12-11) controls the PORTC pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISC register are maintained set when using them as analog inputs. I/O pins configured as analog inputs always read '0'.

12.7.1 PORTC FUNCTIONS AND OUTPUT PRIORITIES

Each PORTC pin is multiplexed with other functions. The pins, their combined functions and their output priorities are shown in Table 12-7.

When multiple outputs are enabled, the actual pin control goes to the peripheral with the highest priority.

Analog input and some digital input functions are not included in the list below. These input functions can remain active when the pin is configured as an output. Certain digital input functions override other port functions and are included in the priority list.

TABLE 12-7: PORTC OUTPUT PRIORITY

Pin Name	Function Priority(1)
RC0	T1OSO (Timer1 Oscillator) SEG40 (ICD) RC0
RC1	T1OSI (Timer1 Oscillator) CCP2(2)/P2A(2) SEG32 (ICD) RC1
RC2	SEG13 (LCD) CCP1/P1A RC2
RC3	SEG17 (LCD) SCL1 (MSSP1) SCK1 (MSSP1) RC3
RC4	SEG16 (LCD) SDA1 (MSSP1) RC4
RC5	SEG12 (LCD) SDO1 (MSSP1) RC5
RC6	SEG27 (LCD) TX1 (EUSART1) CK1 (EUSART1) RC6
RC7	SEG28 (LCD) DT1 (EUSART1) RC7

Note 1: Priority listed from highest to lowest.
2: Default pin (see APFCON register).

15.0 TEMPERATURE INDICATOR MODULE

This family of devices is equipped with a temperature circuit designed to measure the operating temperature of the silicon die. The circuit's range of operating temperature falls between -40°C and +85°C. The output is a voltage that is proportional to the device temperature. The output of the temperature indicator is internally connected to the device ADC.

The circuit may be used as a temperature threshold detector or a more accurate temperature indicator, depending on the level of calibration performed. A one-point calibration allows the circuit to indicate a temperature closely surrounding that point. A two-point calibration allows the circuit to sense the entire range of temperature more accurately. Refer to the application note *AN1333*, *Use and Calibration of the Internal Temperature Indicator* (DS01333) for more details regarding the calibration process.

15.1 Circuit Operation

Figure 15-1 shows a simplified block diagram of the temperature circuit. The proportional voltage output is achieved by measuring the forward voltage drop across multiple silicon junctions.

Equation 15-1 describes the output characteristics of the temperature indicator.

EQUATION 15-1: V_{OUT} RANGES

High Range: $V_{OUT} = V_{DD} - 4V_T$

Low Range: $V_{OUT} = V_{DD} - 2V_T$

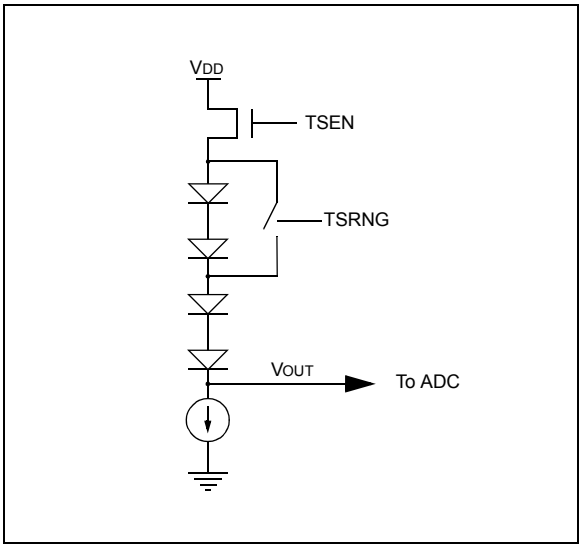
The temperature sense circuit is integrated with the Fixed Voltage Reference (FVR) module. See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information.

The circuit is enabled by setting the TSEN bit of the FVRCON register. When disabled, the circuit draws no current.

The circuit operates in either high or low range. The high range, selected by setting the TSRNG bit of the FVRCON register, provides a wider output voltage. This provides more resolution over the temperature range, but may be less consistent from part to part. This range requires a higher bias voltage to operate and thus, a higher V_{DD} is needed.

The low range is selected by clearing the TSRNG bit of the FVRCON register. The low range generates a lower voltage drop and thus, a lower bias voltage is needed to operate the circuit. The low range is provided for low voltage operation.

FIGURE 15-1: TEMPERATURE CIRCUIT DIAGRAM



15.2 Minimum Operating V_{DD}

When the temperature circuit is operated in low range, the device may be operated at any operating voltage that is within specifications.

When the temperature circuit is operated in high range, the device operating voltage, V_{DD}, must be high enough to ensure that the temperature circuit is correctly biased.

Table 15-1 shows the recommended minimum V_{DD} vs. range setting.

TABLE 15-1: RECOMMENDED V_{DD} VS. RANGE

Min. V_{DD}, TSRNG = 1	Min. V_{DD}, TSRNG = 0
3.6V	1.8V

15.3 Temperature Output

The output of the circuit is measured using the internal Analog-to-Digital Converter. A channel is reserved for the temperature circuit output. Refer to **Section 16.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

Note:	Every time the ADC MUX is changed to the temperature indicator output selection (CHS bit in the ADCCON0 register), wait 500 μsec for the sampling capacitor to fully charge before sampling the temperature indicator output.

REGISTER 16-5: ADRESH: ADC RESULT REGISTER HIGH (ADRESH) ADFM = 1

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	—	—	—	ADRES<9:8>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-2 **Reserved**: Do not use.

bit 1-0 **ADRES<9:8>**: ADC Result Register bits
Upper two bits of 10-bit conversion result

REGISTER 16-6: ADRESL: ADC RESULT REGISTER LOW (ADRESL) ADFM = 1

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
ADRES<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **ADRES<7:0>**: ADC Result Register bits
Lower eight bits of 10-bit conversion result

17.7 Register Definitions: DAC Control

REGISTER 17-1: DACCON0: VOLTAGE REFERENCE CONTROL REGISTER 0

R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	U-0	R/W-0/0
DACEN	DACLPS	DACOE	—	DACPSS<1:0>		—	DACNSS
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **DACEN:** DAC Enable bit
1 = DAC is enabled
0 = DAC is disabled

bit 6 **DACLPS:** DAC Low-Power Voltage State Select bit
1 = DAC Positive reference source selected
0 = DAC Negative reference source selected

bit 5 **DACOE:** DAC Voltage Output Enable bit
1 = DAC voltage level is also an output on the DACOUT pin
0 = DAC voltage level is disconnected from the DACOUT pin

bit 4 **Unimplemented:** Read as ‘0’

bit 3-2 **DACPSS<1:0>:** DAC Positive Source Select bits
00 = V_{DD}
01 = V_{REF}+ pin
10 = FVR Buffer2 output
11 = Reserved, do not use

bit 1 **Unimplemented:** Read as ‘0’

bit 0 **DACNSS:** DAC Negative Source Select bits
1 = V_{REF}-
0 = V_{SS}

REGISTER 17-2: DACCON1: VOLTAGE REFERENCE CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	—	DACR<4:0>				
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **DACR<4:0>:** DAC Voltage Output Select bits

TABLE 17-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE DAC MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR1	ADFVR0	151
DACCON0	DACEN	DACLPS	DACOE	—	DACPSS<1:0>		—	DACNSS	171
DACCON1	—	—	—	DACR<4:0>					171

Legend: — = Unimplemented location, read as ‘0’. Shaded cells are not used with the DAC module.

TABLE 18-3: SUMMARY OF REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELF	ANSF7	ANSF6	ANSF5	ANSF4	ANSF3	ANSF2	ANSF1	ANSF0	141
ANSELG	—	—	—	ANSG4	ANSG3	ANSG2	ANSG1	—	144
CM1CON0	C1ON	C1OUT	C1OE	C1POL	—	C1SP	C1HYS	C1SYNC	178
CM2CON0	C2ON	C2OUT	C2OE	C2POL	—	C2SP	C2HYS	C2SYNC	178
CM1CON1	C1NTP	C1INTN	C1PCH<1:0>		—	—	C1NCH<1:0>		179
CM2CON1	C2NTP	C2INTN	C2PCH<1:0>		—	—	C2NCH<1:0>		179
CM3CON0	C3ON	C3OUT	C3OE	C3POL	—	C3SP	C3HYS	C3SYNC	178
CM3CON1	C3INTP	C3INTN	C3PCH1	C3PCH0	—	—	C3NCH<1:0>		179
CMOUT	—	—	—	—	—	MC3OUT	MC2OUT	MC1OUT	179
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>		151
DACCON0	DACEN	DACLPS	DACOE	—	DACPSS<1:0>		—	DACNSS	171
DACCON1	—	—	—	DACR<4:0>					171
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	90
PIE2	OSFIE	C2IE	C1IE	EEIE	BCLIE	LCDIE	C3IE	CCP2IE	92
PIR2	OSFIF	C2IF	C1IF	EEIF	BCLIF	LCDIF	C3IF	CCP2IF	96
TRISF	TRISF7	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	140
TRISG	—	—	TRISG5	TRISG4	TRISG3	TRISG2	TRISG1	TRISG0	143

Legend: — = unimplemented location, read as '0'. Shaded cells are unused by the comparator module.

23.4.2 FULL-BRIDGE MODE

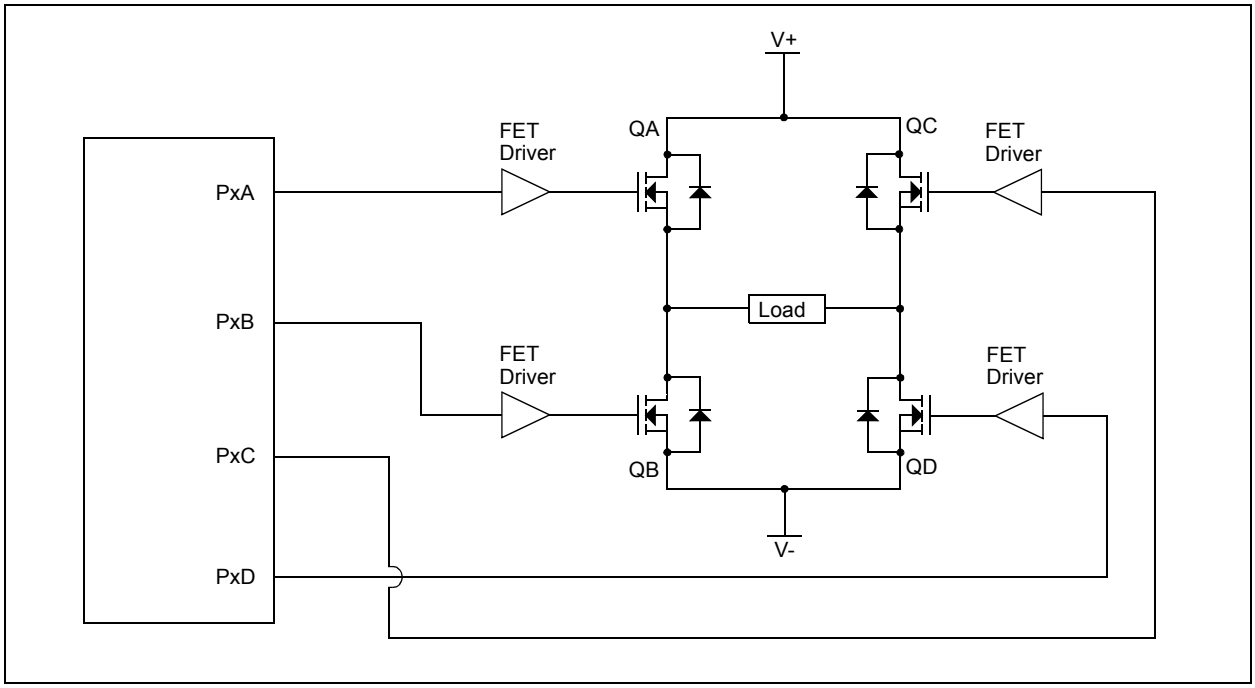
In Full-Bridge mode, all four pins are used as outputs. An example of Full-Bridge application is shown in Figure 23-10.

In the Forward mode, pin CCPx/PxA is driven to its active state, pin PxD is modulated, while PxB and PxC will be driven to their inactive state as shown in Figure 23-11.

In the Reverse mode, PxC is driven to its active state, pin PxB is modulated, while PxA and PxD will be driven to their inactive state as shown Figure 23-11.

PxA, PxB, PxC and PxD outputs are multiplexed with the PORT data latches. The associated TRIS bits must be cleared to configure the PxA, PxB, PxC and PxD pins as outputs.

FIGURE 23-10: EXAMPLE OF FULL-BRIDGE APPLICATION



23.4.2.1 Direction Change in Full-Bridge Mode

In the Full-Bridge mode, the PxM1 bit in the CCPxCON register allows users to control the forward/reverse direction. When the application firmware changes this direction control bit, the module will change to the new direction on the next PWM cycle.

A direction change is initiated in software by changing the PxM1 bit of the CCPxCON register. The following sequence occurs four Timer cycles prior to the end of the current PWM period:

- The modulated outputs (PxB and PxD) are placed in their inactive state.
- The associated unmodulated outputs (PxA and PxC) are switched to drive in the opposite direction.
- PWM modulation resumes at the beginning of the next period.

See Figure 23-12 for an illustration of this sequence.

The Full-Bridge mode does not provide dead-band delay. As one output is modulated at a time, dead-band delay is generally not required. There is a situation where dead-band delay is required. This situation occurs when both of the following conditions are true:

1. The direction of the PWM output changes when the duty cycle of the output is at or near 100%.
2. The turn-off time of the power switch, including the power device and driver circuit, is greater than the turn on time.

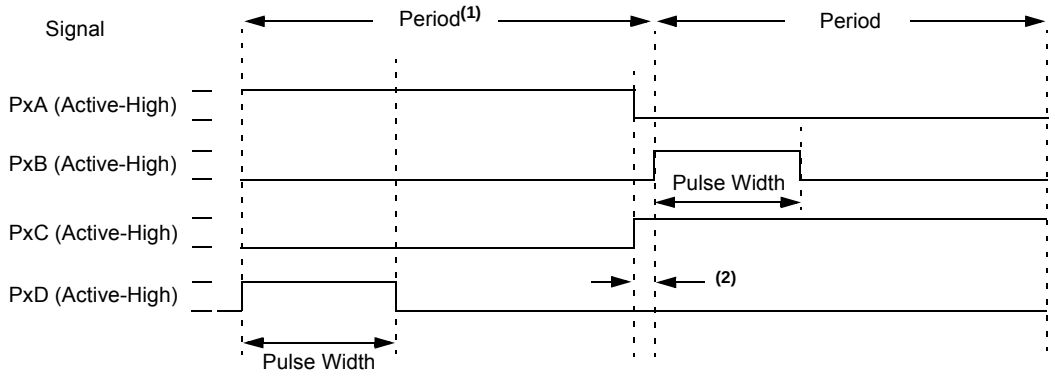
Figure 23-13 shows an example of the PWM direction changing from forward to reverse, at a near 100% duty cycle. In this example, at time t1, the output PxA and PxD become inactive, while output PxC becomes active. Since the turn-off time of the power devices is longer than the turn-on time, a shoot-through current will flow through power devices QC and QD (see Figure 23-10) for the duration of ‘t’. The same phenomenon will occur to power devices QA and QB for PWM direction change from reverse to forward.

If changing PWM direction at high duty cycle is required for an application, two possible solutions for eliminating the shoot-through current are:

1. Reduce PWM duty cycle for one PWM period before changing directions.
2. Use switch drivers that can drive the switches off faster than they can drive them on.

Other options to prevent shoot-through current may exist.

FIGURE 23-12: EXAMPLE OF PWM DIRECTION CHANGE



Note 1: The direction bit PxM1 of the CCPxCON register is written any time during the PWM cycle.

2: When changing directions, the PxA and PxC signals switch before the end of the current PWM cycle. The modulated PxB and PxD signals are inactive at this time. The length of this time is four Timer counts.

REGISTER 23-5: PWMxCON: ENHANCED PWM CONTROL REGISTER(1)

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
PxRSEN	PxDC<6:0>						
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **PxRSEN:** PWM Restart Enable bit

1 = Upon auto-shutdown, the CCPxASE bit clears automatically once the shutdown event goes away; the PWM restarts automatically

0 = Upon auto-shutdown, CCPxASE must be cleared in software to restart the PWM

bit 6-0 **PxDC<6:0>:** PWM Delay Count bits

PxDCx = Number of FOSC/4 (4 * TOSC) cycles between the scheduled time when a PWM signal **should** transition active and the **actual** time it transitions active

Note 1: Bit resets to '0' with Two-Speed Start-up and LP, XT or HS selected as the Oscillator mode or Fail-Safe mode is enabled.

FIGURE 24-21: I²C SLAVE, 10-BIT ADDRESS, RECEPTION (SEN = 0, AHEN = 1, DHEN = 0)

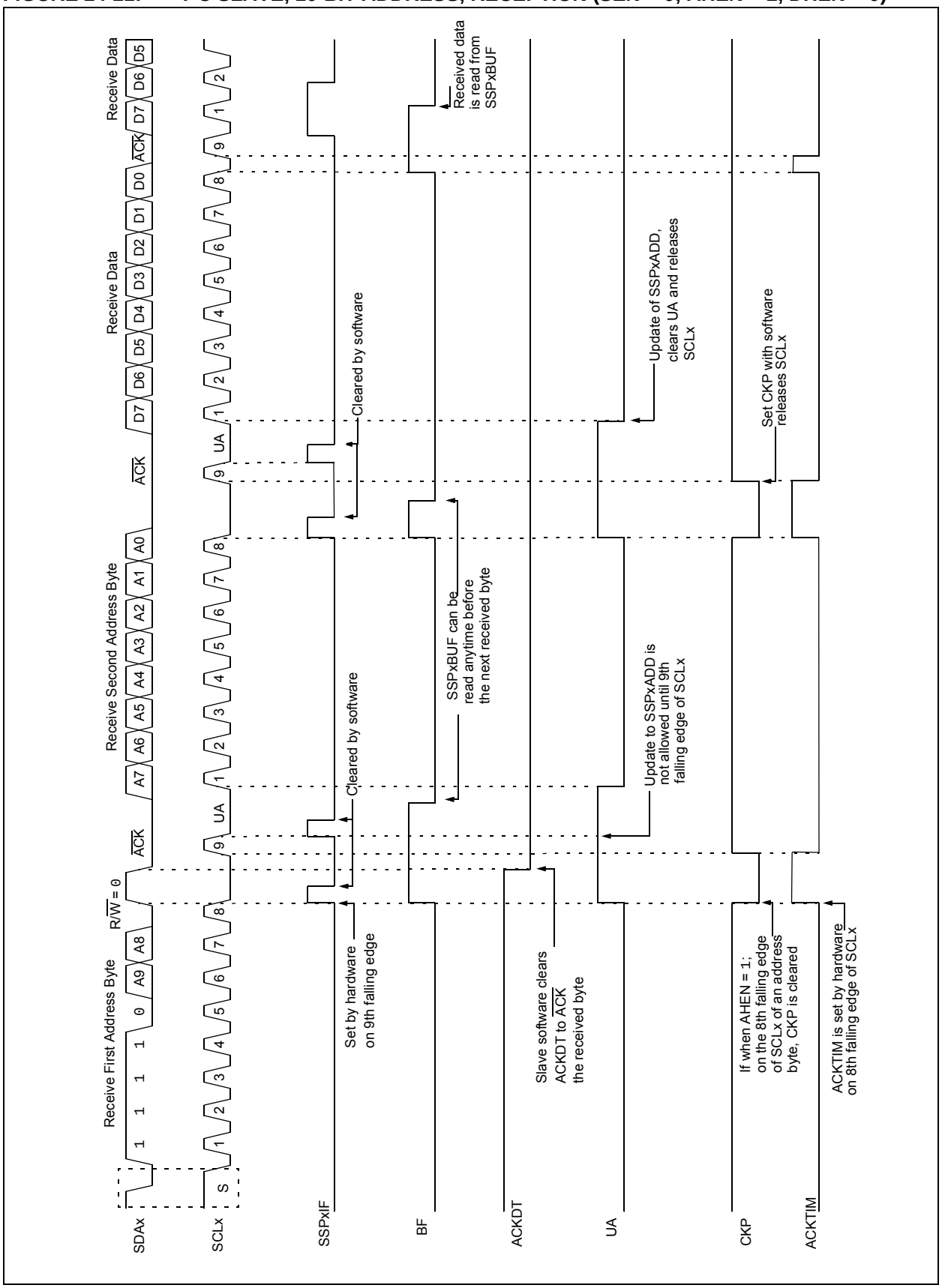
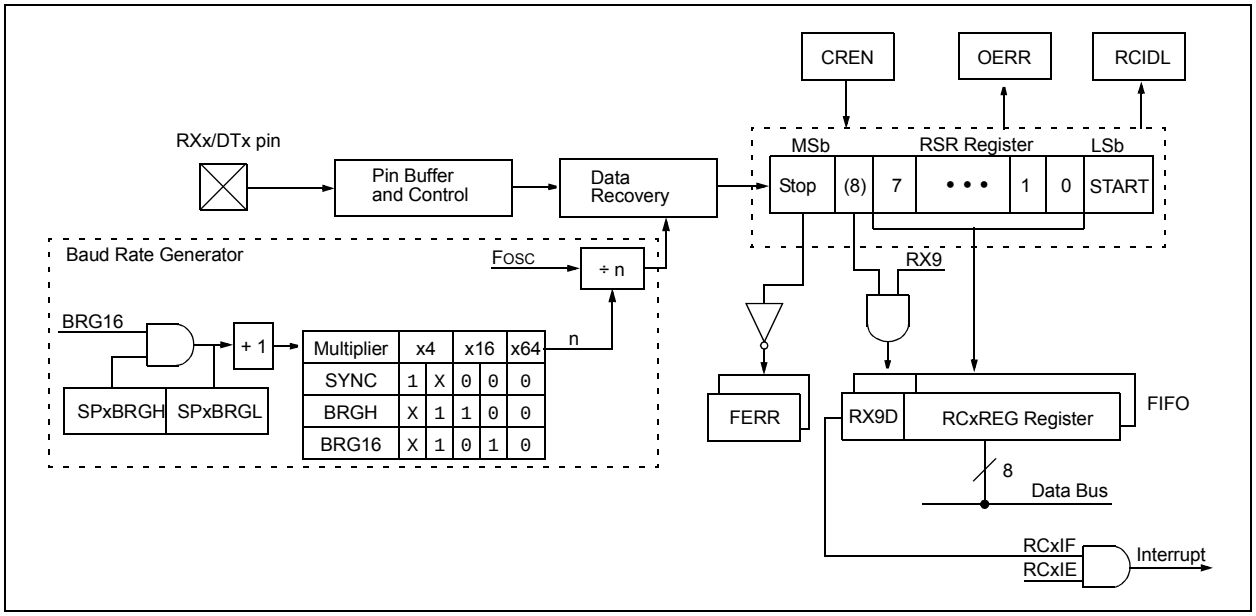


FIGURE 25-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXxSTA)
- Receive Status and Control (RCxSTA)
- Baud Rate Control (BAUDxCON)

These registers are detailed in Register 25-1, Register 25-2 and Register 25-3, respectively.

For all modes of the EUSART operation, the TRIS control bits corresponding to the RXx/DTx and TXx/CKx pins should be set to '1'. The EUSART control will automatically reconfigure the pin from input to output, as needed.

When the receiver or transmitter section is not enabled, then the corresponding RXx/DTx or TXx/CKx pin may be used for general purpose input and output.

25.1.1.5 TSR Status

The TRMT bit of the TXxSTA register indicates the status of the TSR register. This is a read-only bit. The TRMT bit is set when the TSR register is empty and is cleared when a character is transferred to the TSR register from the TXxREG. The TRMT bit remains clear until all bits have been shifted out of the TSR register. No interrupt logic is tied to this bit, so the user needs to poll this bit to determine the TSR status.

Note:	The TSR register is not mapped in data memory, so it is not available to the user.

25.1.1.6 Transmitting 9-Bit Characters

The EUSART supports 9-bit character transmissions. When the TX9 bit of the TXxSTA register is set the EUSART will shift nine bits out for each character transmitted. The TX9D bit of the TXxSTA register is the ninth, and Most Significant, data bit. When transmitting 9-bit data, the TX9D data bit must be written before writing the eight Least Significant bits into the TXxREG. All nine bits of data will be transferred to the TSR shift register immediately after the TXxREG is written.

A special 9-bit Address mode is available for use with multiple receivers. See **Section 25.1.2.7 "Address Detection"** for more information on the Address mode.

25.1.1.7 Asynchronous Transmission Setup:

1. Initialize the SPxBRGH:SPxBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 25.4 "EUSART Baud Rate Generator (BRG)"**).
2. Set the RXx/DTx and TXx/CKx TRIS controls to '1'.
3. Enable the asynchronous serial port by clearing the SYNC bit and setting the SPEN bit.
4. If 9-bit transmission is desired, set the TX9 control bit. A set ninth data bit will indicate that the eight Least Significant data bits are an address when the receiver is set for address detection.
5. Set the SCKP control bit if inverted transmit data polarity is desired.
6. Enable the transmission by setting the TXEN control bit. This will cause the TXxIF interrupt bit to be set.
7. If interrupts are desired, set the TXxIE interrupt enable bit. An interrupt will occur immediately provided that the GIE and PEIE bits of the INTCON register are also set.
8. If 9-bit transmission is selected, the ninth bit should be loaded into the TX9D data bit.
9. Load 8-bit data into the TXxREG register. This will start the transmission.

FIGURE 25-3: ASYNCHRONOUS TRANSMISSION

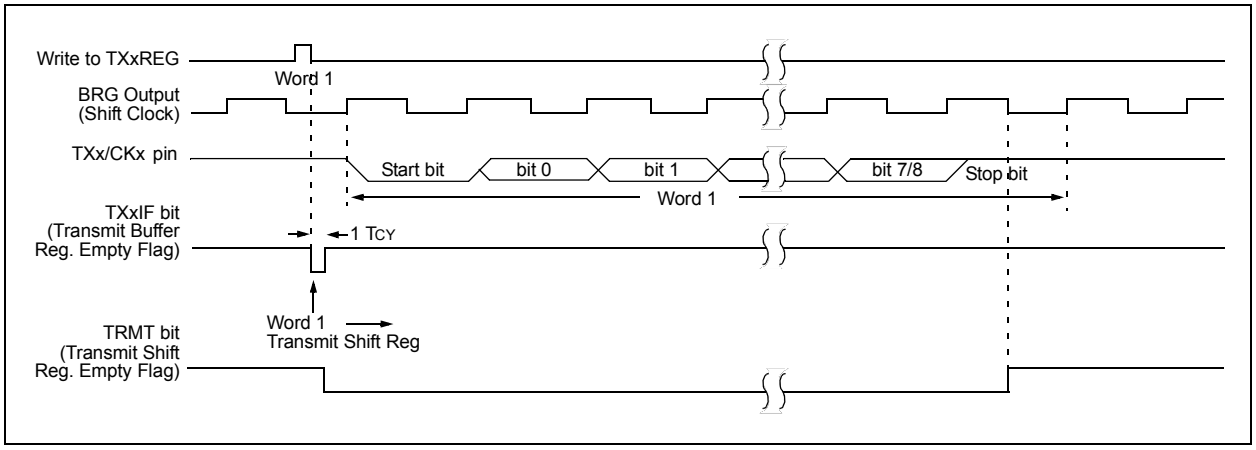
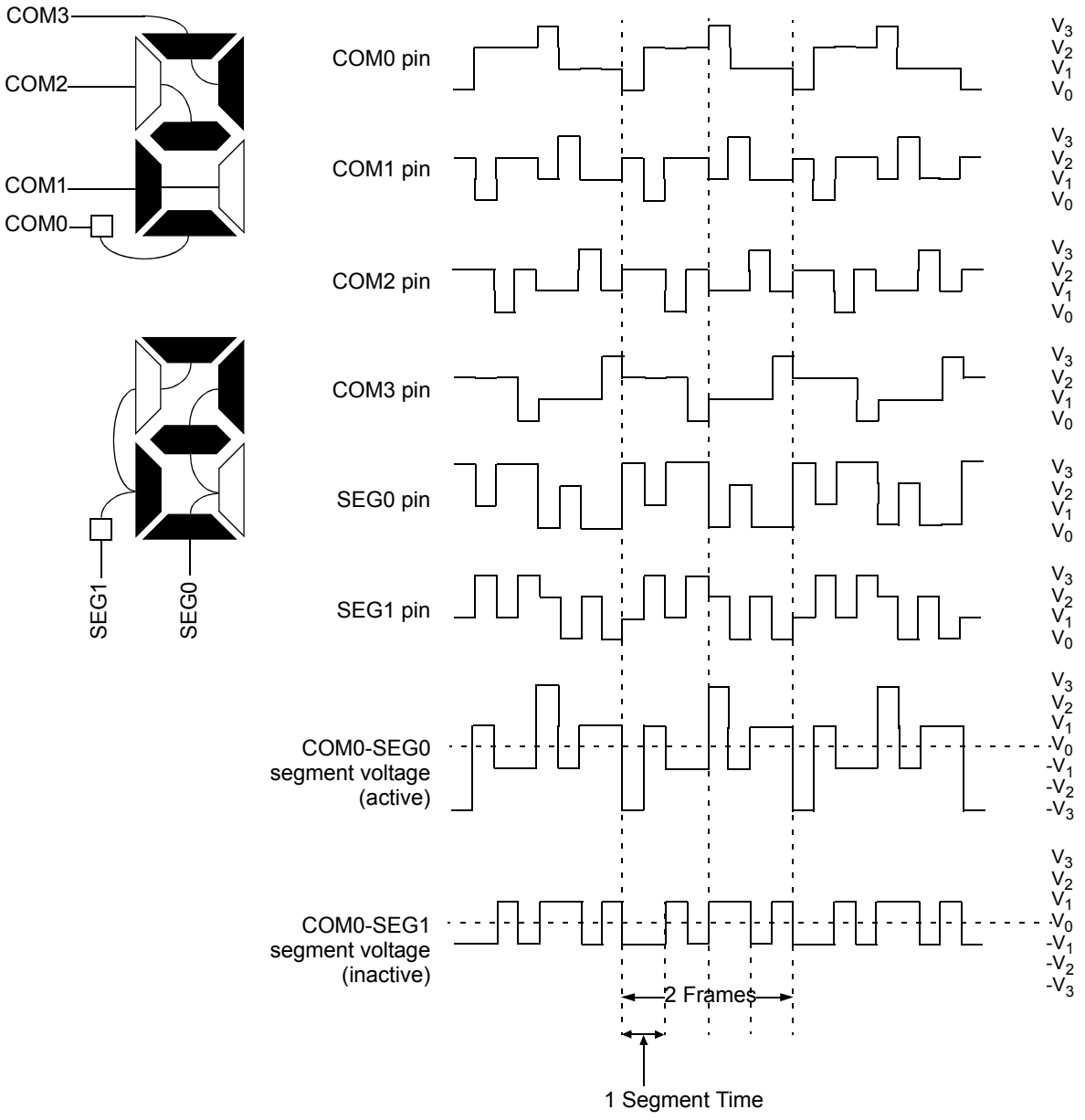


FIGURE 27-18: TYPE-B WAVEFORMS IN 1/4 MUX, 1/3 BIAS DRIVE



Note: 1 Frame = 2 single-segment times.

MOVIW **Move INDFn to W**

Syntax: [*label*] MOVIW ++FSRn
[*label*] MOVIW --FSRn
[*label*] MOVIW FSRn++
[*label*] MOVIW FSRn--
[*label*] MOVIW k[FSRn]

Operands: n ∈ [0,1]
mm ∈ [00,01, 10, 11]
-32 ≤ k ≤ 31

Operation: INDFn → W
Effective address is determined by
- FSR + 1 (preincrement)
- FSR - 1 (predecrement)
- FSR + k (relative offset)

After the Move, the FSR value will be either:
- FSR + 1 (all increments)
- FSR - 1 (all decrements)
- Unchanged

Status Affected: Z

Mode	Syntax	mm
Preincrement	++FSRn	00
Predecrement	--FSRn	01
Postincrement	FSRn++	10
Postdecrement	FSRn--	11

Description: This instruction is used to move data between W and one of the indirect registers (INDFn). Before/after this move, the pointer (FSRn) is updated by pre/post incrementing/decrementing it.

Note: The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the FSRn.

FSRn is limited to the range 0000h - FFFFh. Incrementing/decrementing it beyond these bounds will cause it to wrap around.

MOVLB **Move literal to BSR**

Syntax: [*label*] MOVLB k

Operands: 0 ≤ k ≤ 15

Operation: k → BSR

Status Affected: None

Description: The 5-bit literal 'k' is loaded into the Bank Select Register (BSR).

MOVLP **Move literal to PCLATH**

Syntax: [*label*] MOVLP k

Operands: 0 ≤ k ≤ 127

Operation: k → PCLATH

Status Affected: None

Description: The 7-bit literal 'k' is loaded into the PCLATH register.

MOVLW **Move literal to W**

Syntax: [*label*] MOVLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W)

Status Affected: None

Description: The 8-bit literal 'k' is loaded into W register. The "don't cares" will assemble as '0's.

Words: 1

Cycles: 1

Example:
```
MOVLW   0x5A
```
After Instruction
W = 0x5A

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: 0 ≤ f ≤ 127

Operation: (W) → (f)

Status Affected: None

Description: Move data from W register to register 'f'.

Words: 1

Cycles: 1

Example:
```
MOVWF   OPTION_REG
```
Before Instruction
OPTION_REG = 0xFF
W = 0x4F
After Instruction
OPTION_REG = 0x4F
W = 0x4F

30.3 DC Characteristics: PIC16(L)F1946/47-I/E (Industrial, Extended) (Continued)

PIC16LF1946/47			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC16F1946/47			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Device Characteristics**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**	
						VDD	**Note**
	Supply Current (IDD)(1, 2)						
D013		—	15	40	µA	1.8	FOSC = 500 kHz EC Oscillator Low-Power mode
		—	30	75	µA	3.0	
D013		—	30	60	µA	1.8	FOSC = 500 kHz EC Oscillator Low-Power mode **(Note 5)**
		—	45	85	µA	3.0	
		—	50	90	µA	5.0	
D014		—	140	250	µA	1.8	FOSC = 4 MHz EC Oscillator mode Medium-Power mode
		—	270	400	µA	3.0	
D014		—	160	270	µA	1.8	FOSC = 4 MHz EC Oscillator mode **(Note 5)** Medium-Power mode
		—	270	430	µA	3.0	
		—	320	500	µA	5.0	
D015		—	2.0	3.2	mA	3.0	FOSC = 32 MHz EC Oscillator High-Power mode
		—	2.3	3.9	mA	3.6	
D015		—	2.0	3.2	mA	3.0	FOSC = 32 MHz EC Oscillator High-Power mode **(Note 5)**
		—	2.2	3.9	mA	5.0	
D016		—	3.0	11	µA	1.8	FOSC = 32 kHz, LFINTOSC mode **(Note 4)** -40°C ≤ TA ≤ +85°C
		—	5.0	13	µA	3.0	
D016		—	24	40	µA	1.8	FOSC = 32 kHz, LFINTOSC mode **(Note 4, 5)** -40°C ≤ TA ≤ +85°C
		—	30	48	µA	3.0	
		—	32	58	µA	5.0	

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{MCLR}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2 REXT (mA) with REXT in kΩ.

4: FVR and BOR are disabled.

5: 0.1 µF capacitor on VCAP (RF0).

6: 8 MHz crystal oscillator with 4x PLL enabled.

FIGURE 31-43: IPD, CAPACITIVE SENSING (CPS) MODULE, MEDIUM-CURRENT RANGE, CPSRM = 0, PIC16LF1946/47 ONLY

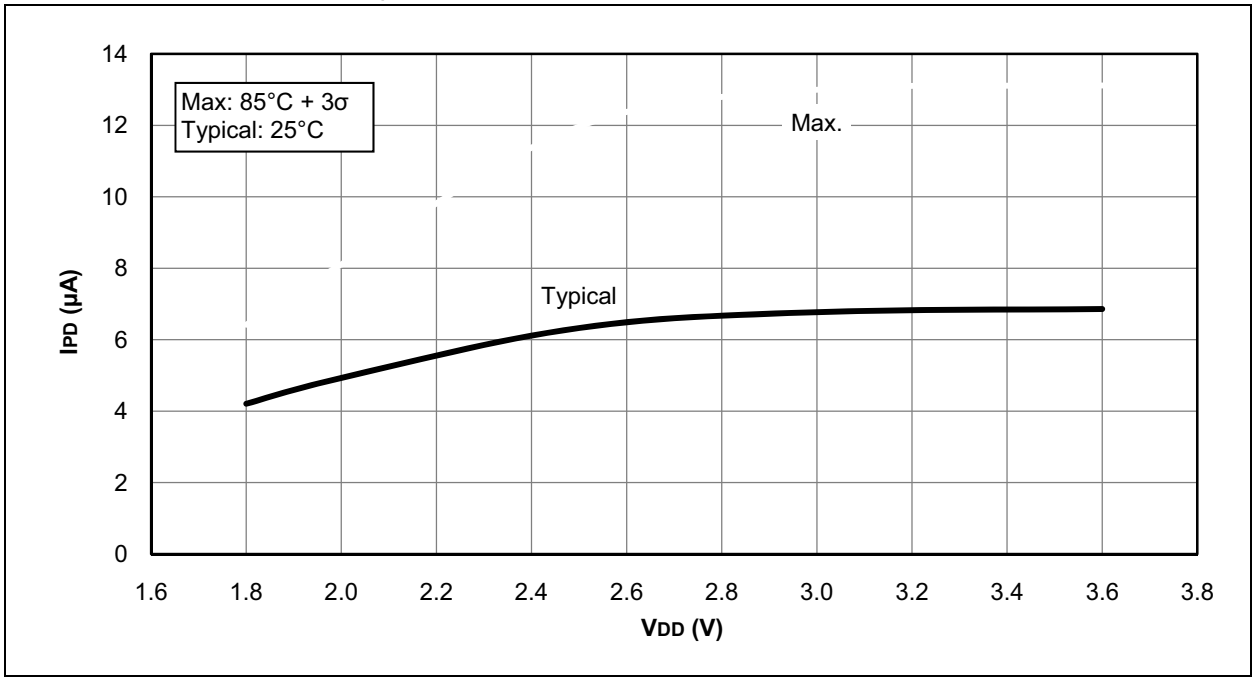


FIGURE 31-44: IPD, CAPACITIVE SENSING (CPS) MODULE, MEDIUM-CURRENT RANGE, CPSRM = 0, PIC16F1946/47 ONLY

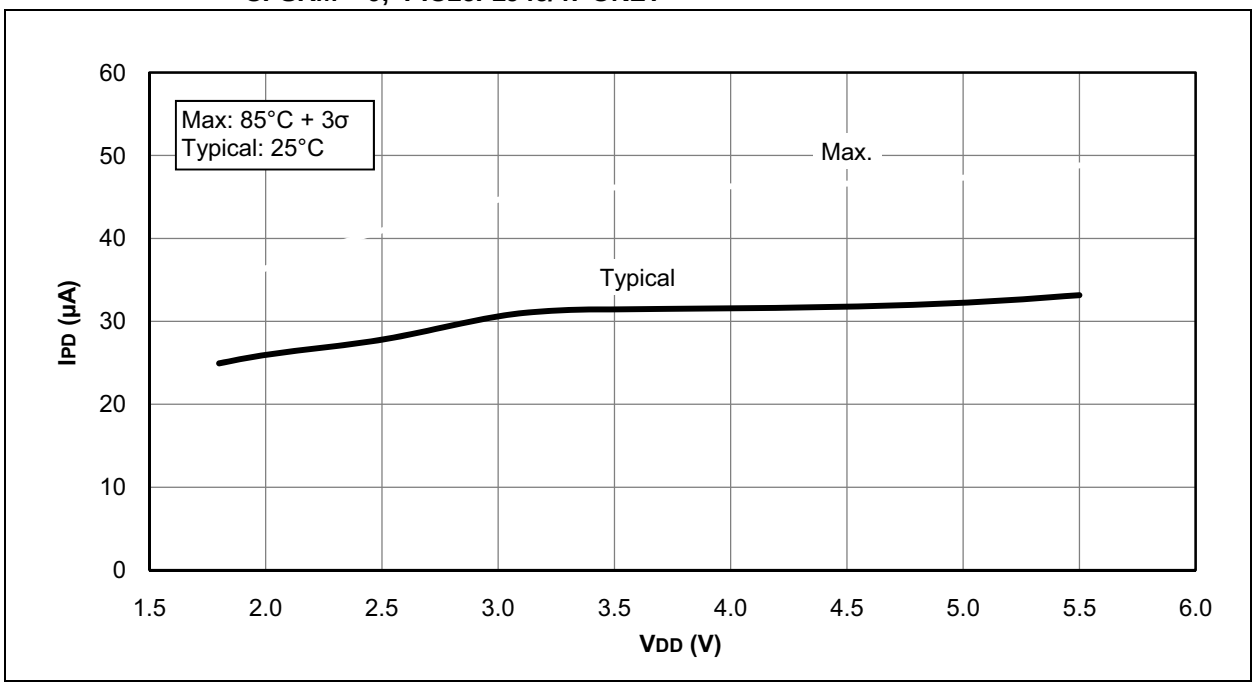


FIGURE 31-45: I_{PD}, CAPACITIVE SENSING (CPS) MODULE, HIGH-CURRENT RANGE, CPSRM = 0, PIC16LF1946/47 ONLY

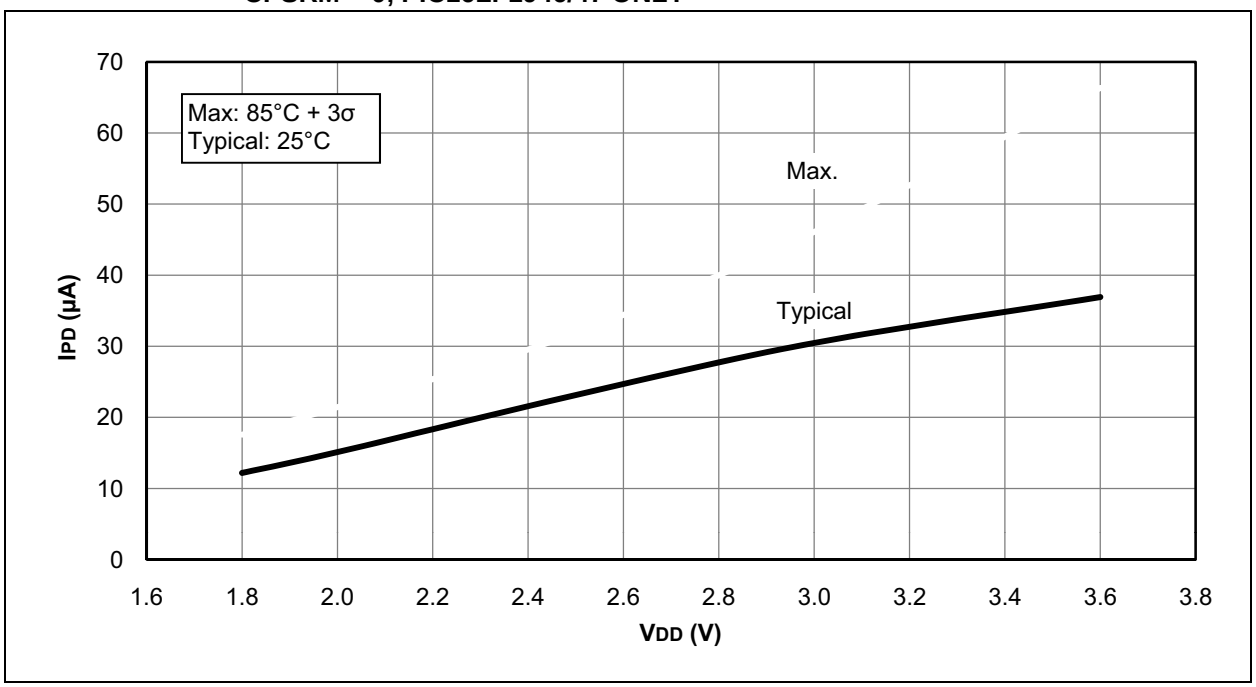
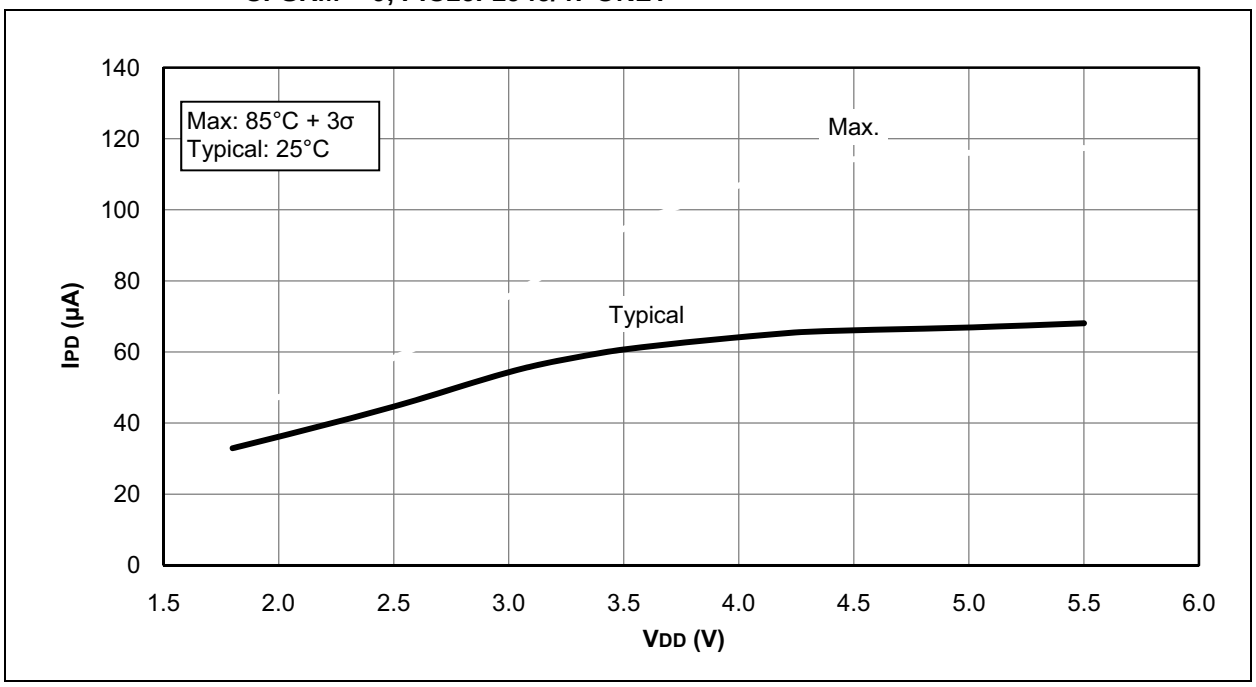


FIGURE 31-46: I_{PD}, CAPACITIVE SENSING (CPS) MODULE, HIGH-CURRENT RANGE, CPSRM = 0, PIC16F1946/47 ONLY



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